

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HUILONG ZHU	11/14/2014
ZHIJIONG LUO	11/14/2014
HAIZHOU YIN	11/14/2014
QINGQING LIANG	11/14/2014
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14407263
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<b>NAME OF SUBMITTER:</b>	JUDSON K. CHAMPLIN
<b>SIGNATURE:</b>	/Judson K. Champlin/
<b>DATE SIGNED:</b>	12/11/2014
<b>Total Attachments: 2</b> source=Assignment#page1.tif	



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## ASSIGNMENT

Attorney Docket No.

H148.0001US1

WHEREAS, we, Huihong ZHU of Poughkeepsie, New York, USA; Zhijiong LUO of Poughkeepsie, New York, USA; Haizhou YIN of Poughkeepsie, New York, USA; and Qingqing LIANG of Lagrangeville, New York, USA (hereinafter referred to as ASSIGNORS), are the inventors of an invention described in an application for Letters Patent entitled SEMICONDUCTOR STRUCTURE AND METHOD FOR MANUFACTURING THE SAME, the application having been executed on even date herewith, and/or being identifiable in the United States Patent and Trademark Office by Application No. 14/407,263, filed 11 December 2014; and

WHEREAS, Institute of Microelectronics, Chinese Academy of Sciences (hereinafter referred to as ASSIGNEE), a corporation organized and existing under the laws of the State of CHINA, and having offices at No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029, CHINA, is desirous of acquiring the entire right, title and interest in and to the invention, the application and any and all Letters Patent(s) or similar legal protection, foreign or domestic, to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, we transfer to Assignee, its successors and assigns, our entire right, title and interest in and to the invention, the above-identified application(s), corresponding domestic and foreign applications claiming rights or benefits to the above-identified application(s) including non-provisional applications, continuation applications, continuing applications, divisional applications, reissue applications, reexamination applications, design applications and continuation-in-part applications, all Letters Patent(s) or similar legal protection issuing thereon, and all rights and benefits under any applicable treaty or convention, including all rights of priority; and we authorize the Director of the United States Patent and Trademark Office or foreign equivalent thereof to issue the Letters Patent or similar legal protection to the Assignee.

We authorize the Assignee, its successors and assigns, to insert in this instrument the filing date and serial number of the application when ascertained.

We authorize the Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in any and all foreign countries.

We represent to the Assignee, its successors and assigns, that we have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. We, our executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignee, its successors and assigns, execute such additional writings and do such additional acts as the Assignee, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries.

Signature of Inventor

Date : 11 / 14 / 2014

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H148.0001US1

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